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April 1st, 2010
Renesas Electronics Corporation

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HD74ALVCH16832

1-to-4 Address Register / Driver with 3-state Outputs

REJ03D0030-0400Z
(Previous ADE-205-214B(Z))
Rev.4.00
Oct.02.2003

Description

This 1-bit to 4-bit address register / driver is designed for 2.3 V to 3.6 V V_{CC} operation.

The device is ideal for use in applications in which a single address bus is driving four separate memory locations. The HD74ALVCH16832 can be used as a buffer or a register, depending on the logic level of the select (\overline{SEL}) input.

When \overline{SEL} is a logic high, the device is in the buffer mode. The outputs follow the inputs and are controlled by the two output enable (\overline{OE}) inputs. Each \overline{OE} controls two groups of seven outputs.

When \overline{SEL} is a logic low, the device is in the register mode. The register is an edge triggered D-type flip flop. On the positive transition of the clock (CLK) input, data at the A inputs is stored in the internal registers. \overline{OE} controls operate the same as in the buffer mode.

When \overline{OE} is a logic low, the outputs are in a normal logic state (high or low logic level). When \overline{OE} is a logic high, the outputs are in the high impedance state.

Neither \overline{SEL} nor \overline{OE} affect the internal operation of the flip flops. Old data can be retained or new data can be entered while the outputs are in the high impedance state.

To ensure the high impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pull up resistor; the minimum value of the resistor is determined by the current sinking capability of the driver.

Active bus hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

Features

- $V_{CC} = 2.3 \text{ V to } 3.6 \text{ V}$
- Typical V_{OL} ground bounce $< 0.8 \text{ V}$ ($@V_{CC} = 3.3 \text{ V, } T_a = 25^\circ\text{C}$)
- Typical V_{OH} undershoot $> 2.0 \text{ V}$ ($@V_{CC} = 3.3 \text{ V, } T_a = 25^\circ\text{C}$)
- High output current $\pm 24 \text{ mA}$ ($@V_{CC} = 3.0 \text{ V}$)
- Bus hold on data inputs eliminates the need for external pull up / pull down resistors

Function Table

| Inputs | | | | Output Y |
|-----------------|------------------|-----|---|----------|
| \overline{OE} | \overline{SEL} | CLK | A | |
| H | X | X | X | Z |
| L | H | X | L | L |
| L | H | X | H | H |
| L | L | ↑ | L | L |
| L | L | ↑ | H | H |

H : High level

L : Low level

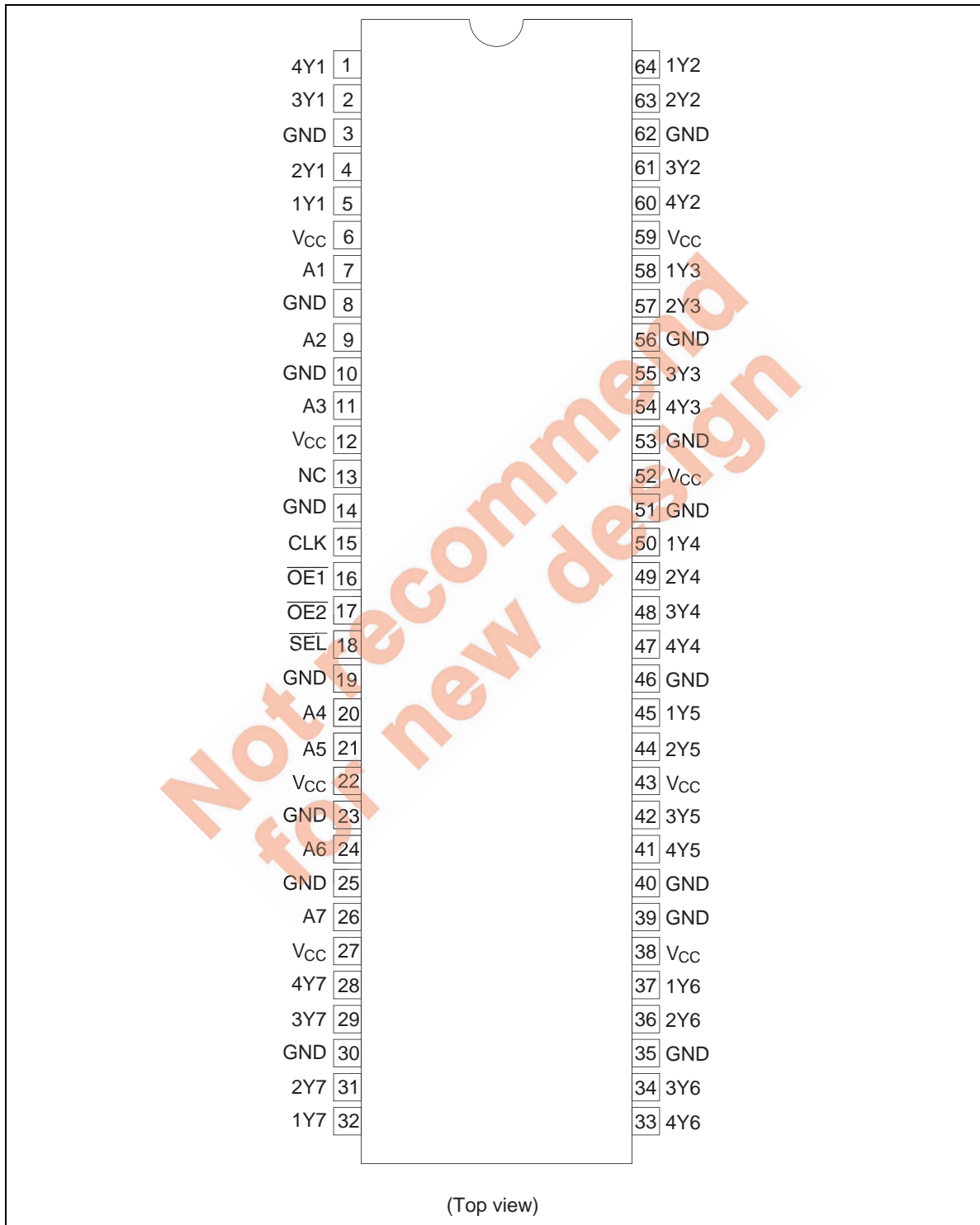
X : Immaterial

Z : High impedance

↑ : Low to high transition

Not recommend
for new design

Pin Arrangement



Absolute Maximum Ratings

| Item | Symbol | Ratings | Unit | Conditions |
|--|-----------------------|------------------------|------------------|-----------------------------|
| Supply voltage | V_{CC} | −0.5 to 4.6 | V | |
| Input voltage ^{*1} | V_I | −0.5 to 4.6 | V | |
| Output voltage ^{*1, 2} | V_O | −0.5 to $V_{CC} + 0.5$ | V | |
| Input clamp current | I_{IK} | −50 | mA | $V_I < 0$ |
| Output clamp current | I_{OK} | ±50 | mA | $V_O < 0$ or $V_O > V_{CC}$ |
| Continuous output current | I_O | ±50 | mA | $V_O = 0$ to V_{CC} |
| V_{CC} , GND current / pin | I_{CC} or I_{GND} | ±100 | mA | |
| Maximum power dissipation at $T_a = 55^\circ\text{C}$ (in still air) ^{*3} | P_T | 1 | W | TSSOP |
| Storage temperature | T_{stg} | −65 to 150 | $^\circ\text{C}$ | |

Notes: Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

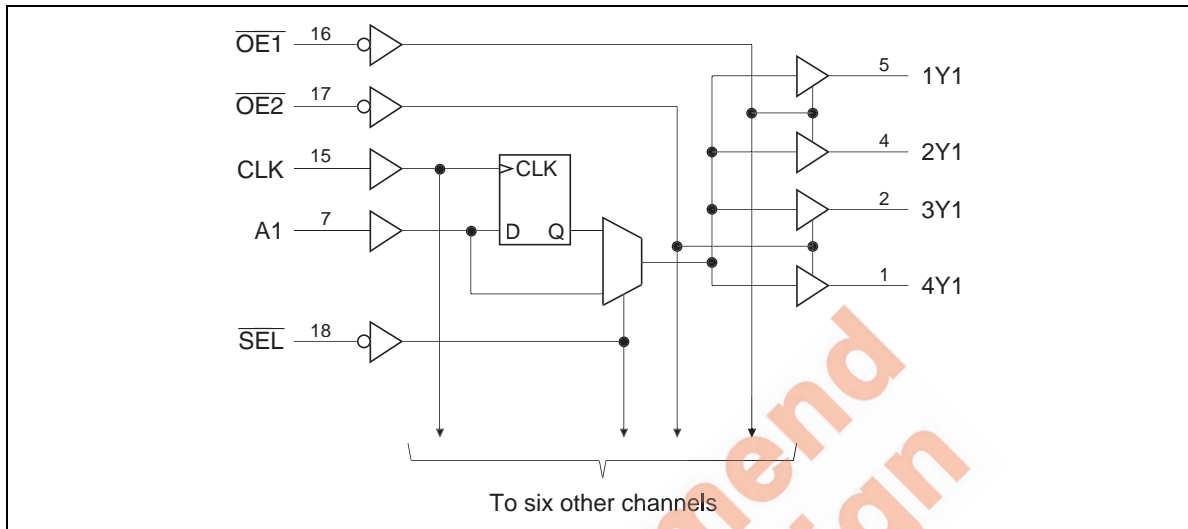
1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

Recommended Operating Conditions

| Item | Symbol | Min | Max | Unit | Conditions |
|------------------------------------|-----------------------|-----|----------|------------------|-------------------------|
| Supply voltage | V_{CC} | 2.3 | 3.6 | V | |
| Input voltage | V_I | 0 | V_{CC} | V | |
| Output voltage | V_O | 0 | V_{CC} | V | |
| High level output current | I_{OH} | — | −12 | mA | $V_{CC} = 2.3\text{ V}$ |
| | | — | −12 | | $V_{CC} = 2.7\text{ V}$ |
| | | — | −24 | | $V_{CC} = 3.0\text{ V}$ |
| Low level output current | I_{OL} | — | 12 | mA | $V_{CC} = 2.3\text{ V}$ |
| | | — | 12 | | $V_{CC} = 2.7\text{ V}$ |
| | | — | 24 | | $V_{CC} = 3.0\text{ V}$ |
| Input transition rise or fall rate | $\Delta t / \Delta v$ | 0 | 10 | ns / V | |
| Operating temperature | T_a | −40 | 85 | $^\circ\text{C}$ | |

Note: Unused control inputs must be held high or low to prevent them from floating.

Logic Diagram



Electrical Characteristics

(Ta = -40 to 85°C)

| Item | Symbol | V _{CC} (V) ^{*1} | Min | Max | Unit | Test Conditions |
|--------------------------|------------------------|-----------------------------------|----------------------|------|------|---|
| Input voltage | V _{IH} | 2.3 to 2.7 | 1.7 | — | V | |
| | | 2.7 to 3.6 | 2.0 | — | | |
| | V _{IL} | 2.3 to 2.7 | — | 0.7 | | |
| | | 2.7 to 3.6 | — | 0.8 | | |
| Output voltage | V _{OH} | 2.3 to 3.6 | V _{CC} -0.2 | — | V | I _{OH} = -100 μA |
| | | 2.3 | 2.0 | — | | I _{OH} = -6 mA, V _{IH} = 1.7 V |
| | | 2.3 | 1.7 | — | | I _{OH} = -12 mA, V _{IH} = 1.7 V |
| | | 2.7 | 2.2 | — | | I _{OH} = -12 mA, V _{IH} = 2.0 V |
| | | 3.0 | 2.4 | — | | I _{OH} = -12 mA, V _{IH} = 2.0 V |
| | | 3.0 | 2.0 | — | | I _{OH} = -24 mA, V _{IH} = 2.0 V |
| | V _{OL} | 2.3 to 3.6 | — | 0.2 | | I _{OL} = 100 μA |
| | | 2.3 | — | 0.4 | | I _{OL} = 6 mA, V _{IL} = 0.7 V |
| | | 2.3 | — | 0.7 | | I _{OL} = 12 mA, V _{IL} = 0.7 V |
| | | 2.7 | — | 0.4 | | I _{OL} = 12 mA, V _{IL} = 0.8 V |
| | | 3.0 | — | 0.55 | | I _{OL} = 24 mA, V _{IL} = 0.8 V |
| | | | | | | |
| Input current | I _{IN} | 3.6 | — | ±5 | μA | V _{IN} = V _{CC} or GND |
| | I _{IN (hold)} | 2.3 | 45 | — | | V _{IN} = 0.7 V |
| | | 2.3 | -45 | — | | V _{IN} = 1.7 V |
| | | 3.0 | 75 | — | | V _{IN} = 0.8 V |
| | | 3.0 | -75 | — | | V _{IN} = 2.0 V |
| | | 3.6 | — | ±500 | | V _{IN} = 0 to 3.6 V ^{*2} |
| | | | | | | |
| Off state output current | I _{OZ} | 3.6 | — | ±10 | μA | V _{OUT} = V _{CC} or GND |
| Quiescent supply current | I _{CC} | 3.6 | — | 40 | μA | V _{IN} = V _{CC} or GND |
| | ΔI _{CC} | 3.0 to 3.6 | — | 750 | μA | V _{IN} = one input at (V _{CC} -0.6) V, other inputs at V _{CC} or GND |

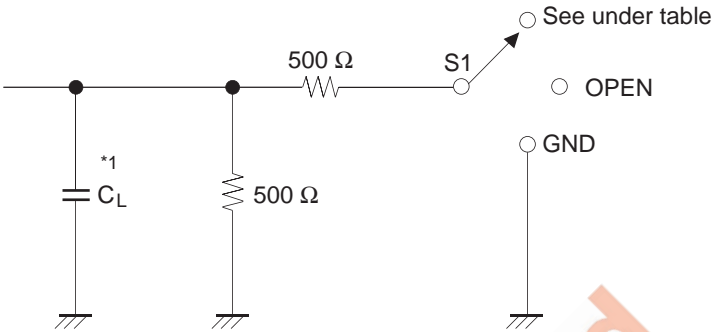
- Notes: 1. For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.
2. This is the bus hold maximum dynamic current required to switch the input from one state to another.

Switching Characteristics

(Ta = -40 to 85°C)

| Item | Symbol | V _{CC} (V) | Min | Typ | Max | Unit | FROM (Input) | TO (Output) |
|-------------------------|------------------|---------------------|-----|-----|-----|------|------------------------|----------------|
| Maximum clock frequency | f _{max} | 2.5±0.2 | 150 | — | — | MHz | | |
| | | 2.7 | 150 | — | — | | | |
| | | 3.3±0.3 | 150 | — | — | | | |
| Propagation delay time | t _{PLH} | 2.5±0.2 | 1.2 | — | 4.0 | ns | A | Y |
| | t _{PHL} | 2.7 | — | — | 4.1 | | | |
| | | 3.3±0.3 | 1.6 | — | 3.6 | | | |
| | | 2.5±0.2 | 1.1 | — | 4.5 | CLK | Y | |
| | | 2.7 | — | — | 4.4 | | | |
| | | 3.3±0.3 | 1.5 | — | 3.9 | | | |
| | | 2.5±0.2 | 1.3 | — | 5.2 | | | |
| | | 2.7 | — | — | 5.2 | | | |
| | | 3.3±0.3 | 1.7 | — | 4.4 | | | |
| | | | | | | | | |
| Output enable time | t _{ZH} | 2.5±0.2 | 1.1 | — | 5.1 | ns | $\overline{\text{OE}}$ | Y |
| | t _{ZL} | 2.7 | — | — | 5.0 | | | |
| | | 3.3±0.3 | 1.2 | — | 4.3 | | | |
| Output disable time | t _{HZ} | 2.5±0.2 | 1.4 | — | 5.5 | ns | $\overline{\text{OE}}$ | Y |
| | t _{LZ} | 2.7 | — | — | 4.7 | | | |
| | | 3.3±0.3 | 1.6 | — | 4.5 | | | |
| Setup time | t _{su} | 2.5±0.2 | 2.0 | — | — | ns | | |
| | | 2.7 | 2.0 | — | — | | | |
| | | 3.3±0.3 | 1.6 | — | — | | | |
| Hold time | t _h | 2.5±0.2 | 0.7 | — | — | ns | | |
| | | 2.7 | 0.5 | — | — | | | |
| | | 3.3±0.3 | 1.1 | — | — | | | |
| Pulse width | t _w | 2.5±0.2 | 3.3 | — | — | ns | | |
| | | 2.7 | 3.3 | — | — | | | |
| | | 3.3±0.3 | 3.3 | — | — | | | |
| Input capacitance | C _{IN} | 3.3 | — | 4.5 | — | pF | Control inputs | |
| | | 3.3 | — | 5.0 | — | | Data inputs | |
| Output capacitance | C _O | 3.3 | — | 7.5 | — | pF | Outputs | |

Test Circuit

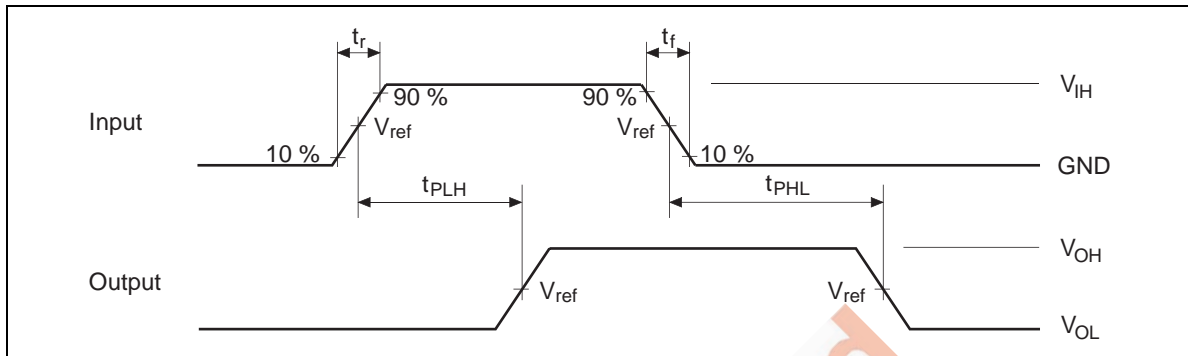


Load Circuit for Outputs

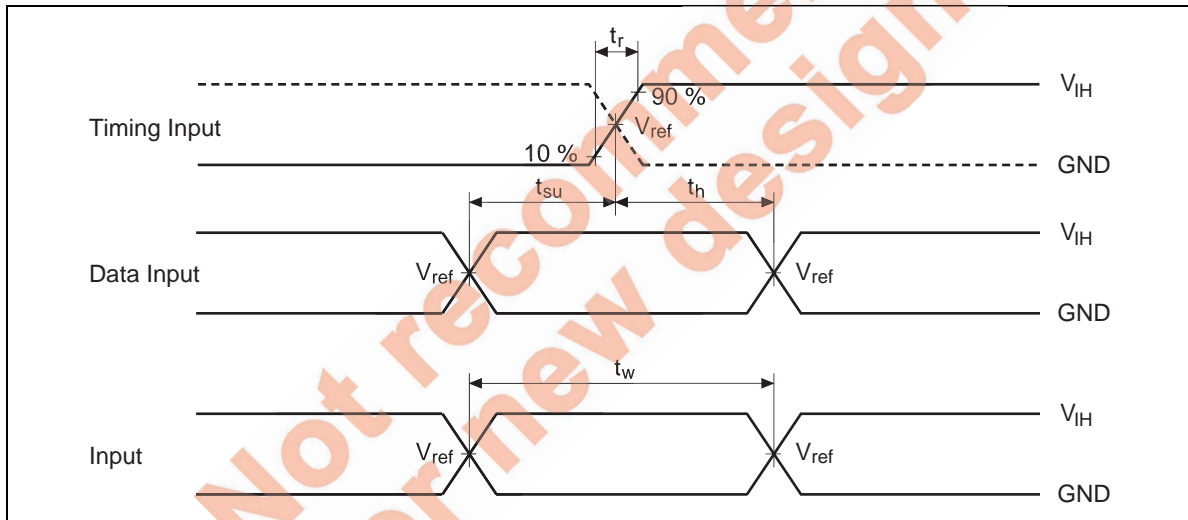
| Symbol | V _{CC} =2.5±0.2V | V _{CC} =2.7V, 3.3±0.3V |
|---|---------------------------|------------------------------------|
| t _{PLH} / t _{PHL} | OPEN | OPEN |
| t _{su} / t _h / t _w | | |
| t _{ZH} / t _{HZ} | GND | GND |
| t _{ZL} / t _{LZ} | 2 × V _{CC} | 6.0 V |
| C _L | 30 pF | 50 pF |

Note: 1. C_L includes probe and jig capacitance.

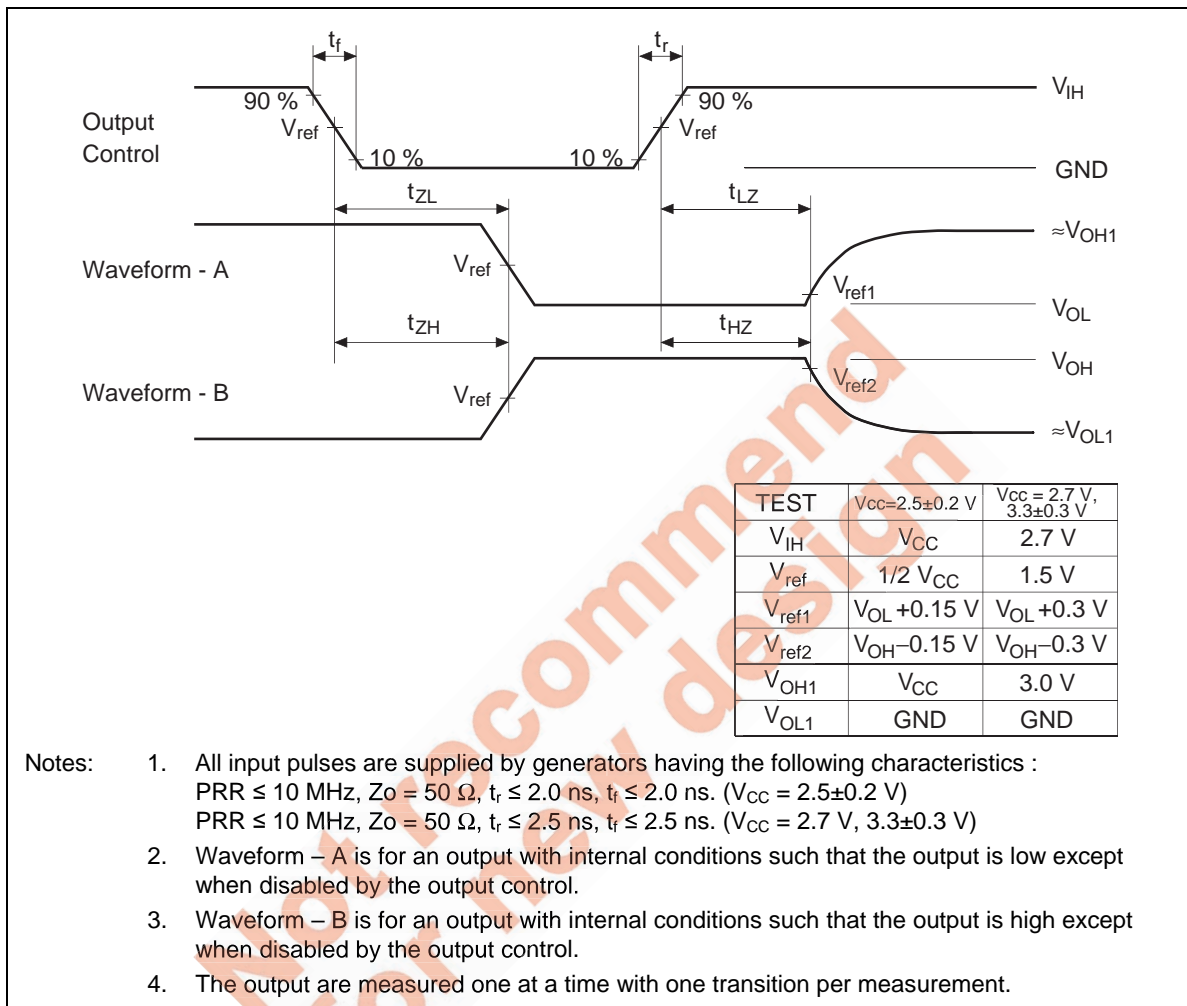
Waveforms – 1



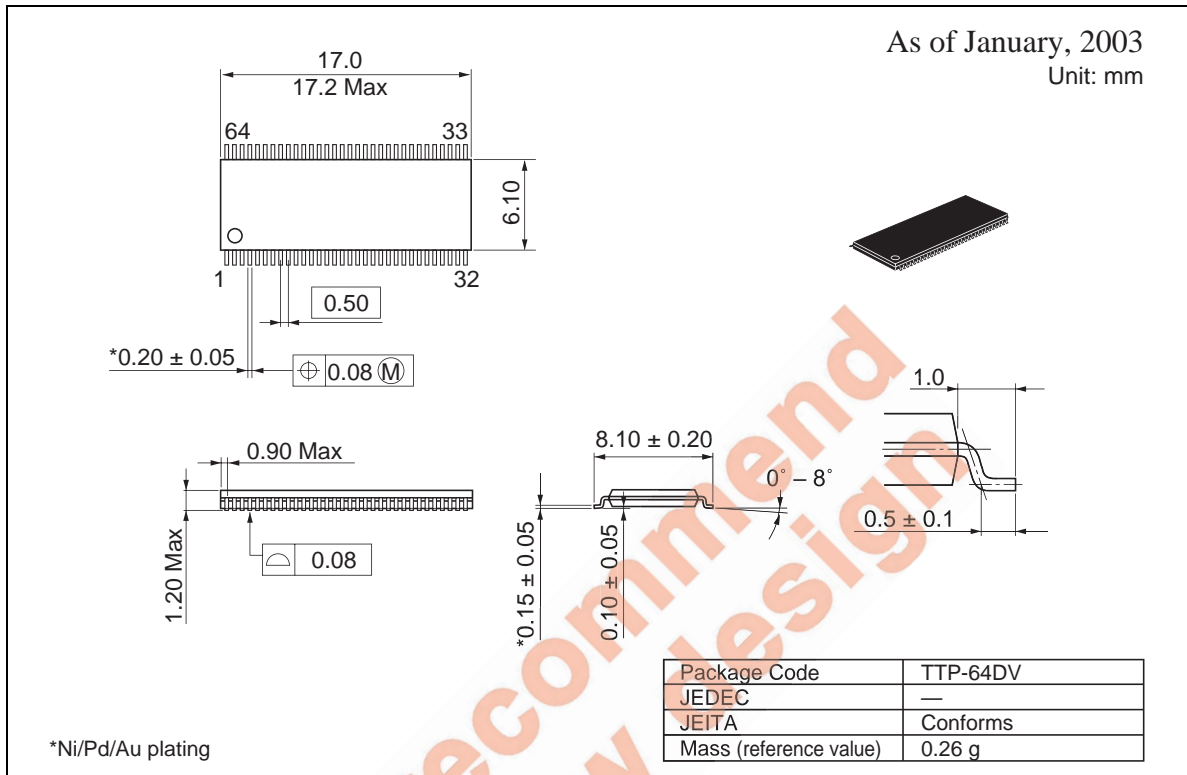
Waveforms – 2



Waveforms – 3



Package Dimensions



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